



**PCN# 20131203000
Conversion to Cu bond wire
Change Notification / Sample Request**

Date: 12/9/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20131203000

Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TRF3705IRGET	null
TRF37T05IRGET	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20131203000			PCN Date:	12/09/2013
Title:	Conversion to Cu bond wire				
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services
Proposed 1st Ship Date:	03/09/2014	Estimated Sample Availability:		12/05/2013	
Change Type:					
<input type="checkbox"/> Assembly Site	<input checked="" type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials	
<input type="checkbox"/> Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification	
<input type="checkbox"/> Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process	
<input type="checkbox"/> Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process	
	<input type="checkbox"/>	Part number change			
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the qualification of Cu as a bond wire option for the selected devices shown below. All listed devices will remain in current assembly facility and there will be no other BOM changes.					
Reason for Change:					
Continuity of supply. 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties 2) Maximize flexibility within our Assembly/Test production sites. 3) Cu is easier to obtain and stock					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
None					
Product Affected					
TRF3705IRGER	TRF3705IRGET	TRF37T05IRGER	TRF37T05IRGET		

Qualification Data			
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.			
Qual Vehicle: TRF37T05IRGE (MSL 2-260C)			
Package Construction Details			
Assembly Site:	Clark-AT	Mold Compound:	4208625
# Pins-Designator, Family:	24-RGE, QFN	Mount Compound:	4207768
Lead Finish	NiPdAuAg	Bond Wire:	0.80Mil Cu

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results		
Reliability Test	Conditions	Sample Size / Fail
Electrical Characterization	Side by Side (Au vs. Cu)	Pass
ESD CDM	+/- 250V, 500V	3/0
ESD HBM	+/- 500V, 1000V, 1500V	3/0
Latch-up	(per JESD78)	6/0

Reference Qualification Data				
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qual Vehicle: CDC750RGC (MSL 3-260C)				
Package Construction Details				
Assembly Site:	Clark AT	Mold Compound:	4208625	
# Pins-Designator, Family:	64-RGC, QFN	Mount Compound:	4207768	
Lead Finish	NiPdAu	Bond Wire:	0.8mil Cu/0.8mil Au	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions		Sample Size/Fail	
			Lot#1	Lot#2
**High Temp. Storage Bake	170C (420 hrs)		77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)		77/0	77/0
**Autoclave	121C, 2 atm (96 Hrs)		77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)		77/0	77/0
Ball Bond Shear	76 balls, 3 units min		Pass	Pass
Bond Pad Cratering Check			Pass	Pass
Bond Pull	76 Wire, 3 units min		Pass	Pass
Notes **- Preconditioning sequence: Level 3-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com